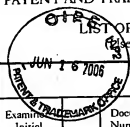


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## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
CME	AA 3,706,094	12/1972	COLE ET AL	342	44	
CME	AB 3,750,167	07/1973	GEHMAN ET AL.	342	44	
CME	AC 3,780,368	12/1973	NORTHEVED ET AL.	342	44	
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CME	AJ 4,418,411	11/1983	STREITZEL	340	870.16	

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							Yes	No
CME	AK	DE 41 20 265 A1	6/1991	Germany (Mitsubishi) See US 5,274,221 (prev. cited)	G06K	7/01	Abs	
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## OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

CME	AN	CASSON, K., et al., "High Temperature Packaging: Flip Chip on Flexible Laminate", <u>Surface Mount Technology</u> , pp. 19-20 (1/1992)
CME	AO	JOHNSON, R.W., "Polymer Thick Films: Technology and Materials", <u>Circuits Manufacturing</u> (reprint), 4 pages (7/1982)
CME	AP	GILLES, K., "Using SM Devices on Flexible Circuitry", <u>ELECTRI-ONICS</u> , pp. 20-23 (3/1986)

EXAMINER DATE CONSIDERED

C. Kurland 7/13/06

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.